

11-21-2006

FORM PTO-1595
(Rev. 08/05)

Docket No.: 069576-0169

103339153
PATENT IS ONLY

EET

U.S. DEPARTMENT OF COMMERCE
Patent and Trademark Office

To the Director of the U. S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

1. Name of Conveying Party(ies)

Byoung Hwa LEE, Hae Suk CHUNG, Dong Seok PARK, Min
Cheol PARK, Sang Soo PARK, Sung Kwon WIAdditional name(s) of conveying party(ies) attached? ☐ Yes ☐ No

3. Nature of Conveyance/Execution Date(s)

Execution Date(s): October 16, 2006

- ☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Joint Research Agreement
☐ Government Interest Assignment
☐ Executive Order 9424, Confirmatory License
☐ Other

2. Name and address of receiving party(ies)

Name: SAMSUNG ELECTRO-MECHANICALS CO.
LTD

Internal Address:

Address: 314 Maetan-3-dong, Youngtong-ku,
Suwon, Kyungki-do, REPUBLIC OF KOREAAdditional name(s) & address(es) attached? ☐ Yes ☐ No

4. Application or patent number(s):

A. Patent Application No(s).

☒ This document is being filed together with a new application

B. Patent No(s).

Additional numbers attached? ☐ Yes ☐ No

5. Name and address to whom correspondence concerning document should be mailed:

Name: MCDERMOTT WILL & EMERY LLP

Internal Address:

Street Address: 600 13th Street, N.W.

City: Washington State: D. C. Zip: 20005-3096

Phone Number: 202.756.8000

Fax Number: 202.756.8087

Email Address:

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 1.21(h) & 3.41) \$40.00

- ☐ Authorized to be charged by credit card
☒ Authorized to be charged to deposit account
☐ Enclosed
☐ None required (government interest not affecting title)nt

8. Payment Information:

- a. Credit Card Last 4 Numbers 500417
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9. Signature.

Stephen A. Becker, 26,527

November 13, 2006

Name and Registration No. of Person Signing

Signature

Total number of pages including cover sheet, attachments and documents:

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PATENT

REEL: 018578 FRAME: 0171

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

(1) <u>LEE, Byoung Hwa</u>	(5) <u>PARK, Sang Soo</u>
(2) <u>CHUNG, Hae Suk</u>	(6) <u>WI, Sung Kwon</u>
(3) <u>PARK, Dong Seok</u>	(7) _____
(4) <u>PARK, Min Cheol</u>	(8) _____

who have made a certain new and useful invention, hereby sell, assign and transfer unto
SAMSUNG ELECTRO-MECHANICS CO., LTD.

314 Maetan-3-dong, Youngtong-ku, Suwon, Kyungki-do, Republic of Korea

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled
MULTILAYER CHIP CAPACITOR

(a) for which an application for United States Letters Patent was filed on _____,
 and identified by United States Serial No. _____; or

(b) for which an application for United States Letters Patent was executed on _____,

and the undersigned hereby authorize and request the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefor and any and all extensions, divisions, reissues, substitutes, renewals, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agree to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the dates indicated aside our signatures:

INVENTORS

DATE SIGNED

1) <u><i>Byoung</i></u> Name: LEE, Byoung Hwa	<u>2006. 10. 16</u>
2) <u><i>Ha Suk</i></u> Name: CHUNG, Hae Suk	<u>2006. 10. 16</u>
3) <u><i>Park</i></u> Name: PARK, Dong Seok	<u>2006. 10. 16</u>
4) <u><i>Min</i></u> Name: PARK, Min Cheol	<u>2006. 10. 16</u>
5) <u><i>Sang Soo</i></u> Name: PARK, Sang Soo	<u>2006. 10. 16</u>
6) <u><i>WI</i></u> Name: WI, Sung Kwon	<u>2006. 10. 16</u>

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